

Item P19-1181

Wafer Tuck Point Blades

Easily removes grout and mortar from between bricks and concrete blocks in less than half the time of a conventional tuck blade. The unique design of Wafer Tuck Point Blades lets the users easily grind away damaged mortar by allowing the grinder to work at a higher speed than what can be achieved with a standard style tuck point blade. Available in two-blade and three-blade designs with 1/4" and 3/8" thicknesses, respectively.

Item	Description	Attributes
19-1181	Premium Double Wafer Tuck	Diameter: 4 1/2" Double 1/4": 1/4"
19-1185	Premium Double Wafer Tuck	Diameter: 5" Double 1/4": yes
19-1363	Premium Double Wafer Tuck	Diameter: 7" Double 1/4": yes
19-1183	Premium Triple Wafer Tuck	Diameter: 4 1/2" Triple 3/8": yes
19-1365	Premium Triple Wafer Tuck	Diameter: 5" Triple 3/8": yes
19-1366	Premium Triple Wafer Tuck	Diameter: 7" Triple 3/8": yes